

AD-A191 895

A PRACTICAL INTERFEROMETRIC TECHNIQUE FOR MASK/WAFER  
ALIGNMENT DURING PROXIMITY PRINTING(U) NAVAL OCEAN  
SYSTEMS CENTER SAN DIEGO CA J L BARTELT ET AL. MAY 87

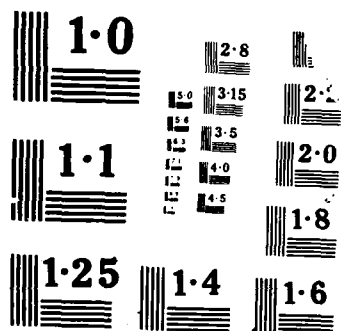
1/1

UNCLASSIFIED

F/G 9/1

NL





②

AD-A191 895

UNCLAS  
SECURITY CL

REPORT DOCUMENTATION PAGE

1a. REPORT SECURITY CLASSIFICATION <b>UNCLASSIFIED</b>			1b. RESTRICTIVE MARKINGS	
2a. SECURITY CLASSIFICATION AUTHORITY			3. DISTRIBUTION/AVAILABILITY OF REPORT Approved for public release; distribution is unlimited.	
2b. DECLASSIFICATION/DOWNGRADING SCHEDULE			5. MONITORING ORGANIZATION REPORT NUMBER(S)	
4. PERFORMING ORGANIZATION REPORT NUMBER(S)			7a. NAME OF MONITORING ORGANIZATION <b>DTIC ELECTE</b> MAR 11 1988	
6a. NAME OF PERFORMING ORGANIZATION <b>Naval Ocean Systems Center</b>	6b. OFFICE SYMBOL (if applicable)	7b. ADDRESS (City, State and ZIP Code)		
8a. NAME OF FUNDING/SPONSORING ORGANIZATION <b>Naval Air Systems Command</b>		9. PROCUREMENT INSTRUMENT IDENTIFICATION NUMBER		
8b. OFFICE SYMBOL (if applicable) <b>NAVAIR</b>		10. SOURCE OF FUNDING NUMBERS		
8c. ADDRESS (City, State and ZIP Code) <b>San Diego, CA 92152-5000</b>		PROGRAM ELEMENT NO <b>78011N</b>	PROJECT NO <b>ET50</b>	TASK NO <b>R1050</b>
8d. ADDRESS (City, State and ZIP Code) <b>Washington, DC 20361</b>		AGENCY ACCESSION NO. <b>DN388 597</b>		
11. TITLE (Include Security Classification) <b>A Practical Interferometric Technique for Mask/Wafer Alignment During Proximity Printing</b>				
12. PERSONAL AUTHOR(S) <b>I. Lagnado</b>				
13a. TYPE OF REPORT <b>Journal Article</b>	13b. TIME COVERED FROM _____ TO _____	14. DATE OF REPORT (Year, Month, Day) <b>May 1987</b>		15. PAGE COUNT
16. SUPPLEMENTARY NOTATION				
17. COSATI CODES			18. SUBJECT TERMS (Continue on reverse if necessary and identify by block number)	
FIELD	GROUP	SUB-GROUP		
19. ABSTRACT (Continue on reverse if necessary and identify by block number) A new automated technique for sensing translational/rotational mask-to-wafer alignment will be presented that is useful with proximity printing processes such as masked ion beam or x-ray lithography. The technique is based on computer interpretation of fringe patterns created by laser beams diffracted from unique grating structures on both the mask and the wafer. It requires no moving parts and features a simple optical configuration that uses a dielectric cube beamsplitter to recombine the diffracted beams. Being an interferometric technique, precision better than 20 nm is easily achieved, while the novel grating structure and fringe analysis provides a capture range in excess of 20 $\mu$ m. Additional key features of the technique are that it is insensitive to variations in the gap between mask and wafer and that its performance does not degrade with changes in surface reflectivity or topography as device wafers are processed. A single channel of the grating alignment technique has been implemented and tested in a laboratory bench fixture. The required mathematics, computer code, and experimental results will be discussed. This work was funded in part by the Naval Ocean Systems Center (NOSC) under contract number N66001-84-C-0110.				
20. DISTRIBUTION/AVAILABILITY OF ABSTRACT <input type="checkbox"/> UNCLASSIFIED/UNLIMITED <input checked="" type="checkbox"/> SAME AS RPT <input type="checkbox"/> DTIC USERS			21. ABSTRACT SECURITY CLASSIFICATION <b>UNCLASSIFIED</b>	
22a. NAME OF RESPONSIBLE INDIVIDUAL <b>I. Lagnado</b>			22b. TELEPHONE (include Area Code) <b>619-225-6735</b>	22c. OFFICE SYMBOL <b>Code 5503</b>

DD FORM 1473, 84 JAN

83 APR EDITION MAY BE USED UNTIL EXHAUSTED  
ALL OTHER EDITIONS ARE OBSOLETE

UNCLASSIFIED  
SECURITY CLASSIFICATION OF THIS PAGE

A practical interferometric technique for mask/wafer  
alignment during proximity printing

by

J. L. Bartelt and R. D. Olney  
Hughes Research Laboratories +  
3011 Malibu Canyon Road  
Malibu, CA 90265

Abstract

A new automated technique for sensing translational/rotational mask-to-wafer alignment will be presented that is useful with proximity printing processes such as masked ion beam or x-ray lithography. The technique is based on computer interpretation of fringe patterns created by laser beams diffracted from unique grating structures on both the mask and the wafer. It requires no moving parts and features a simple optical configuration that uses a dielectric cube beamsplitter to recombine the diffracted beams. Being an interferometric technique, precision better than 20 nm is easily achieved, while the novel grating structure and fringe analysis provides a capture range in excess of 20  $\mu\text{m}$ . Additional key features of the technique are that it is insensitive to variations in the gap between mask and wafer and that its performance does not degrade with changes in surface reflectivity or topography as device wafers are processed. A single channel of the grating alignment technique has been implemented and tested in a laboratory bench fixture. The required mathematics, computer code, and experimental results will be discussed.

This work was funded in part by the Naval Ocean Systems Center (NOSC) under contract number N66001-84-C-0110.

Accession For	
NTIS GRA&I	
DTIC TAB	
Unannounced	
Justification	
By	
Distribution/	
Availability Code	
Dist	Avail and/or Special
A-1	

88 3 03 090

A practical interferometric technique for mask/wafer alignment during proximity printing

by

J. L. Bartelt and R. D. Olney  
Hughes Research Laboratories  
3011 Malibu Canyon Road  
Malibu, CA 90265

Abstract

A new automated technique for sensing translational/rotational mask-to-wafer alignment will be presented that is useful with proximity printing processes such as masked ion beam or x-ray lithography. The technique is based on computer interpretation of fringe patterns created by laser beams diffracted from unique grating structures on both the mask and the wafer. It requires no moving parts and features a simple optical configuration that uses a dielectric cube beamsplitter to recombine the diffracted beams. Being an interferometric technique, precision better than 20 nm is easily achieved, while the novel grating structure and fringe analysis provides a capture range in excess of 20  $\mu\text{m}$ . Additional key features of the technique are that it is insensitive to variations in the gap between mask and wafer and that its performance does not degrade with changes in surface reflectivity or topography as device wafers are processed. A single channel of the grating alignment technique has been implemented and tested in a laboratory bench fixture. The required mathematics, computer code, and experimental results will be discussed.

This work was funded in part by the Naval Ocean Systems Center (NOSC) under contract number N66001-84-C-0110.

Accession For

NTIS GRA&I

DTIC TAB

Unannounced

Justification

By

Distribution/

Availability Code

Dist

Special

A-1

END

DATE

FILMED

5-88  
DTIC